What is claimed is:

1. A chip type power inductor comprising:

a stack body where a magnetic substance which forms a magnetic core stacked with a plurality of layers and non-magnetic layers inserted to inside of the magnetic substance which forms a magnetic core are formed as one unit;

coil patterns formed on either upper surfaces or lower surfaces of the plurality of layers of the magnetic substance which forms a magnetic core;

via holes formed at the plurality of layers constituting the magnetic substance which forms a magnetic core in order to electrically connect the coil patterns;

cover layers in contact with upper and lower surfaces of the magnetic substance which forms a magnetic core; and

external electrodes electrically connected to a part of the coil patterns.

2. The chip type power inductor of claim 1, wherein each layer constituting the magnetic substance which forms a magnetic core includes:

a non-magnetic electrode layer having an opening at a center thereof and electrode patterns on at least one surface of upper and lower surfaces thereof; and

a magnetic layer positioned at the center opening and lateral surfaces of the non-magnetic electrode layer,

in which the non-magnetic electrode layer and the magnetic layer constitute one layer.

3. The chip type power inductor of claim 1, wherein the cover layer further includes a non-magnetic layer.

4. The chip type power inductor of claim 1, further comprising a buffer layer constituted as a non-magnetic layer between upper and lower surfaces of the magnetic substance which forms a magnetic core and the cover layer.

5. The chip type power inductor of claim 1, wherein the non-magnetic layer is composed of B_2O_3-SiO_2 based glass, Al_2O_3-SiO_2 based glass, or other ceramic material.

6. The chip type power inductor of claim 1, wherein the magnetic substance is composed of Ni-based ferrite, Ni-Zn based ferrite, Ni-Zn-Cu based ferrite, and etc.

7. A fabrication method of a chip type power inductor comprising:

preparing green sheets that a magnetic layer and a non-magnetic layer are respectively formed on a carrier film;

forming cutting lines on the magnetic layer green sheet and the non-magnetic layer green sheet;

forming via holes on the non-magnetic layer green sheet where the cutting lines are formed, and forming an electrode pattern at an upper surface of the non-magnetic layer green sheet;

picking up unnecessary parts from the magnetic layer green sheet and the

non-magnetic layer green sheet and thus corresponding remaining parts of the magnetic substance to the picked up parts of the non-magnetic substance or corresponding the picked up parts of the magnetic substance to remaining parts of the non-magnetic substance;

stacking a plurality of layers by constituting the magnetic layer and the non-magnetic layer where via holes and electrode patterns are formed as one unit in a state that a non-magnetic layer where cutting lines and electrode patterns are not formed is inserted;

stacking a cover layer composed of a magnetic layer at upper and lower surfaces of the stacked layers;

firing the stacked body; and

forming external electrodes at an outer surface of the fired stack body.

8. The method of claim 7, wherein the magnetic layer or the non-magnetic layer on the carrier film are respectively formed by using a doctor blade tape casting method.

9. The method of claim 7, wherein the electrode pattern of an upper surface of the non-magnetic layer green sheet is formed by a screen printing.

10. A chip type power inductor fabricated by a method of claim 7.